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## **Opportunities for dual-use technologies: Components**

Avenue Beaulieu 25, room S1, Brussels 28 June 2016

Agenda

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09:00	Registration
09:30	COMPONENTS: A DUAL-USE TECHNOLOGY: SETTING THE SCENE
	Introductory remarks by Khalil Rouhana, Director EC Denis Roger, Director EDA Bert De Colvenaer, Executive Director ECSEL-JU
10:00 11:00	RELIABILITY, THERMAL MANAGEMENT AND ROBUSTNESS – moderated by Nikolaos Kyrloglou (EC) Innovative Nano and Micro Technologies for Advanced Thermo and Mechanical Interface (NANOTHERM) André Cardoso, NANIUM S.A Miniaturization and Ruggedization for 3D Packaging (PERU) and Thermal Management of Hot Spots Claude Sarno, Thales Questions and Answers
11:15	COFFEE BREAK
11:30	RF COMPONENTS AND III-V TECHNOLOGIES – moderated by Wolfgang Scheidler (EDA)  Optimal SIC substRates for Integrated Microwave and Power CircuitS (OSIRIS)  Sylvain Delage, III-V Lab  A Micromachined Heterogeneous Integration Platform for THz Systems (M3TERA)  Franz Dielacher, Infineon Technologies Austria AG  EUGANIC and MAGNUS in context to the European GaN supply chain for Microwave Applications  Klaus Beilenhoff, UMS and Patrick Gremillet, Thales
12:45	Questions and Answers
13:00	LUNCH BREAK
	ADVANCED DIGITAL COMPONENTS - moderated by Yves Gigase (ECSEL)  DEep SubMicron System-on-Chip (SoC) for Harsh Environment applicaTions using EuRopean Technologies (DEMETER)  François Martin, STMicroelectronics  ATHENIS_3D: 3D integration of heterogeneous technologies for high voltage and high temperature applications  Ewald Wachmann, Senior Manager Process R&D, ams AG  System-on-chip (SoC) as an enabler for future Defence applications  Hans Brugger, Airbus DS Electronics and Border Security GmbH
15:00	Questions and Answers
	PANEL DUAL-USE, DUAL-BENEFITS  Moderated by Alun Foster (ECSEL)  Bryan Wells (UK MoD), Thierry Tingaud (STM), Paul Anciaux (DG GROW), Jouni Latti (ESA)  CONCLUSIONS AND WAY AHEAD